

OL-PCF85133

Bare die; 110 bumps

10 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|---------------------|
| Terminal position code | U (upper) |
| Package type descriptive code | UC |
| Package type industry code | UC |
| Package style descriptive code | UC (uncased chip) |
| Package style suffix code | NA (not applicable) |
| Package body material type | X (other) |
| IEC package outline code | --- |
| JEDEC package outline code | --- |
| JEITA package outline code | --- |
| Mounting method type | S (surface mount) |
| Issue date | 26-10-2011 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-----|-----|-------|-----|------|
| D | package length | - | - | 4.156 | - | mm |
| E | package width | - | - | 1.069 | - | mm |
| A | seated height | - | - | 0.38 | - | mm |
| e | nominal pitch | - | - | 0.054 | - | mm |
| n ₂ | actual quantity of termination | - | - | 110 | - | |



2. Package outline

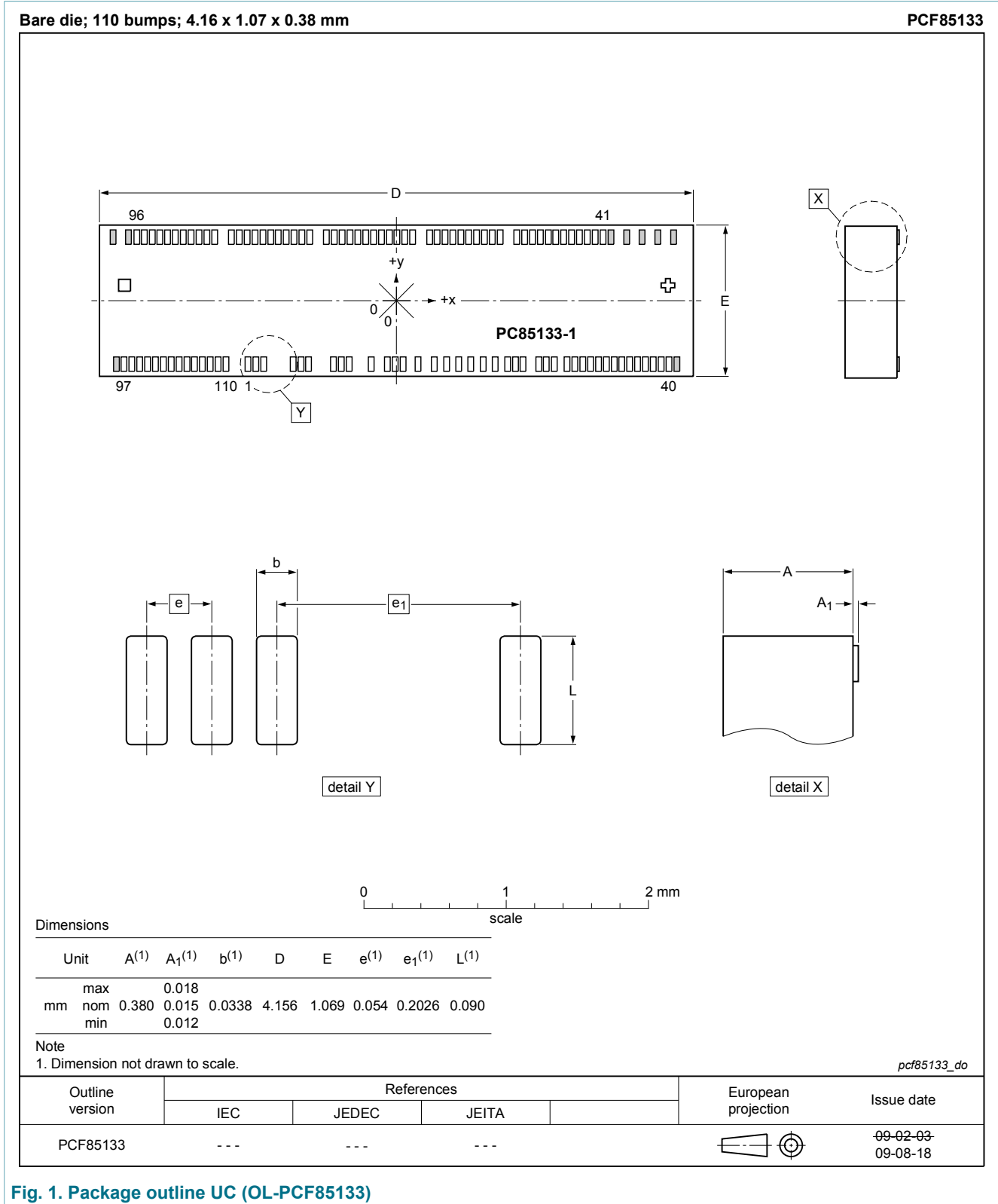


Fig. 1. Package outline UC (OL-PCF85133)

3. Legal information

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